



# APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
<p><b>TO:</b></p> <p><b>Part No.:</b></p> <p><b>Customer's Part No.:</b></p>	<p>Please return this copy as a certification of your approval</p> <p><b>Checked &amp; Approved by:</b></p> <p><b>Date:</b></p>

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Part No.	:	SF0407
Pages	:	6
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Revision	:	1.1

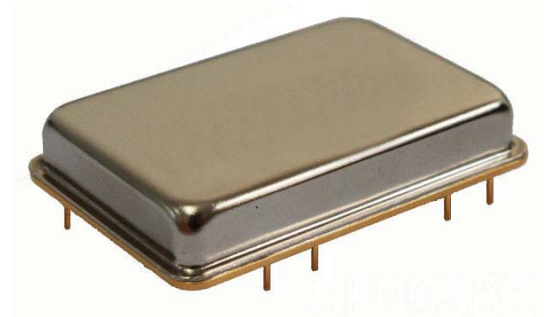
<b>Prepared by:</b>	梁浩
<b>Checked by:</b>	
<b>Approved by:</b>	

**Application**

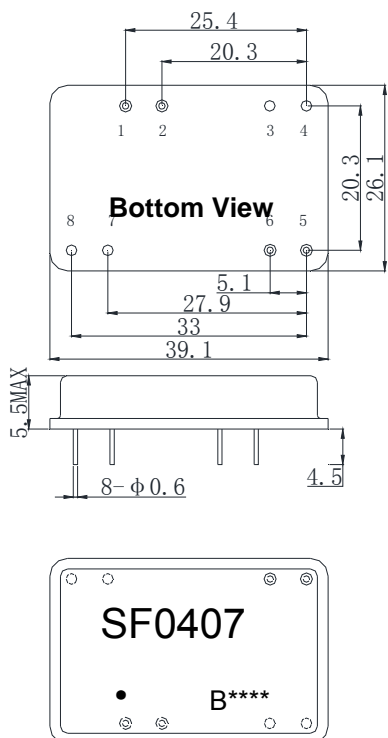
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 0.22/1.8 MHz

**Features**

- RoHS compatible
- Package size 39.1x26.1x7.50mm<sup>3</sup>
- Package Code DIP3926J
- Electrostatic Sensitive Device(ESD)



**Package Dimensions (Unit: mm)**



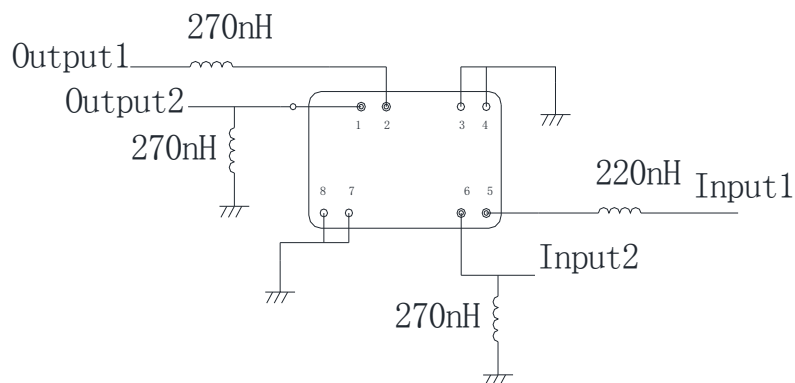
**Pin Configuration**

Pin No.	Description
5	Input1
6	Input2
2	Output1
1	Output2
3,4,7,8	Ground

**Marking Description**

<b>S</b>	Trademark
<b>F</b>	SAW Filter
<b>0407</b>	Part Number
●	Pin 1
<b>B****</b>	Year Code & Serial No.

**Test Circuit(Bottom View)**



**Performance****Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

**Electronic Characteristics**

Test Temperature: 25°C ± 2°C

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

## Case input 5 output 2

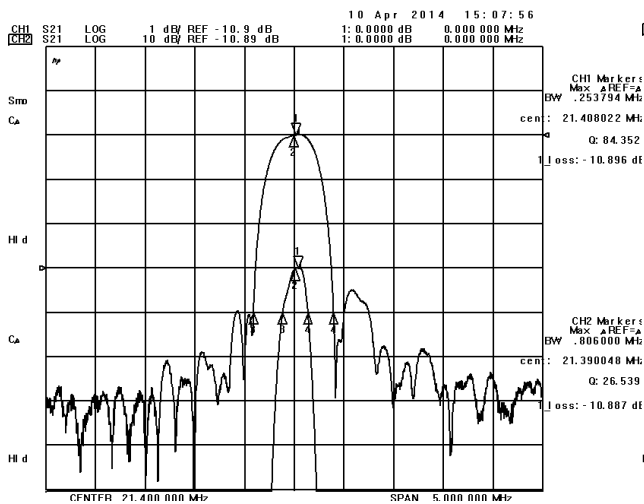
		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		21.4		MHz
Insertion Loss	IL		10.9	12.0	dB
Amplitude Ripple (p-p) 21.26-21.54MHz	Δα		1.5	3.0	dB
1 dB Bandwidth	BW <sub>1dB</sub>	0.22	0.26		MHz
Group Delay Ripple 21.26-21.54MHz	GDR		240	260	ns
Absolute Attenuation	α				
18.90-20.30MHz		40	50		dB
21.00MHz		30	33		dB
21.80 MHz		30	43		dB
22.50-23.90MHz		40	50		dB

## Case input6 output 1

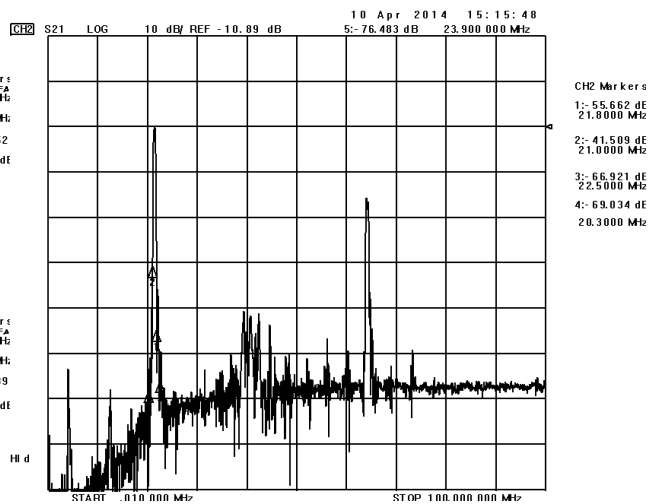
		Minimum	Typical	Maximum	Unit
Center Frequency	f <sub>c</sub>		21.4		MHz
Insertion Loss	IL		10.5	12.0	dB
Amplitude Ripple (p-p) 20.55-22.25MHz	Δα		0.5	0.8	dB
1 dB Bandwidth	BW <sub>1dB</sub>	1.8	2.4		MHz
Group Delay Ripple 20.55-22.25MHz	GDR		100	150	ns
Absolute Attenuation	α				
11.40-18.40MHz		40	42		dB
24.40-31.40MHz		40	42		dB

Frequency Characteristics(Case input 5 output 2)

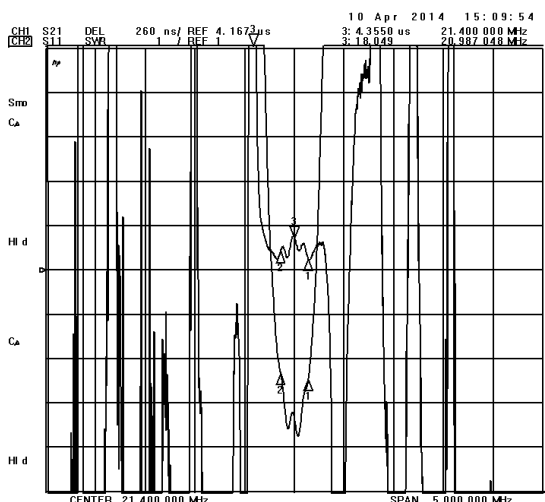
Frequency Response



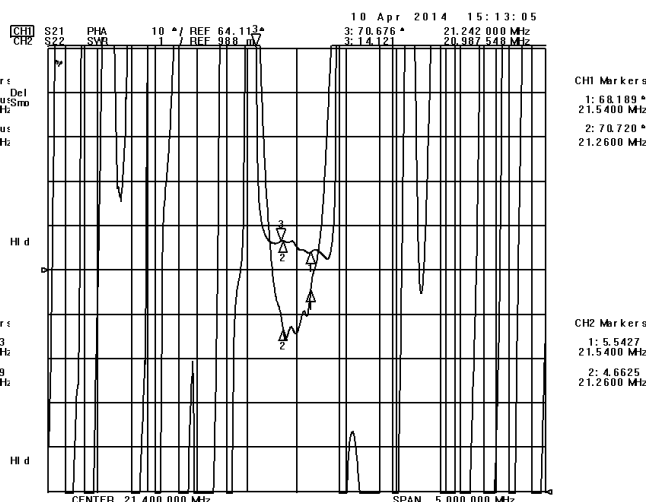
Frequency Response (wideband)



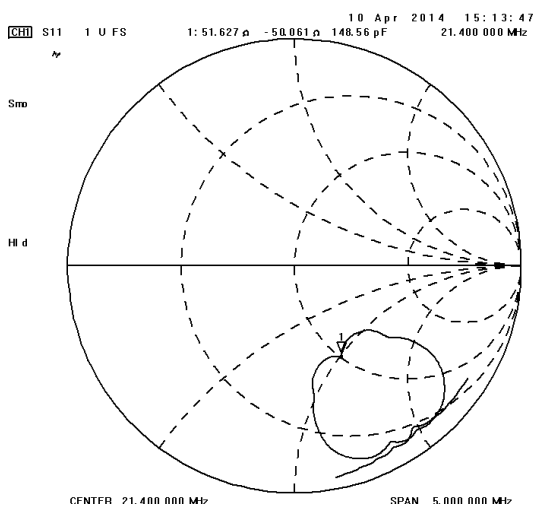
Delay Ripple & S11 VSWR



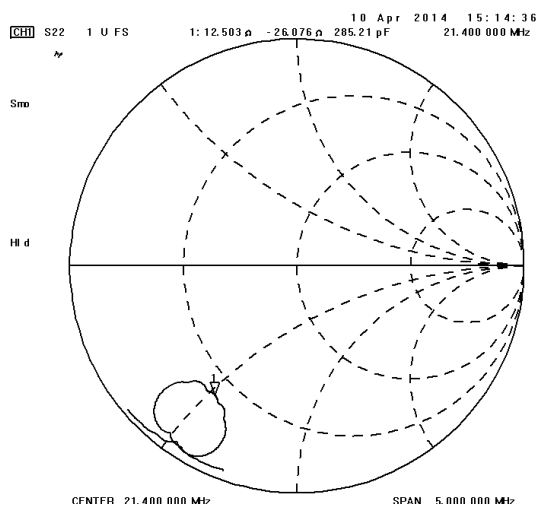
Phase Linearity & S22 VSWR



S11 Smith Chart

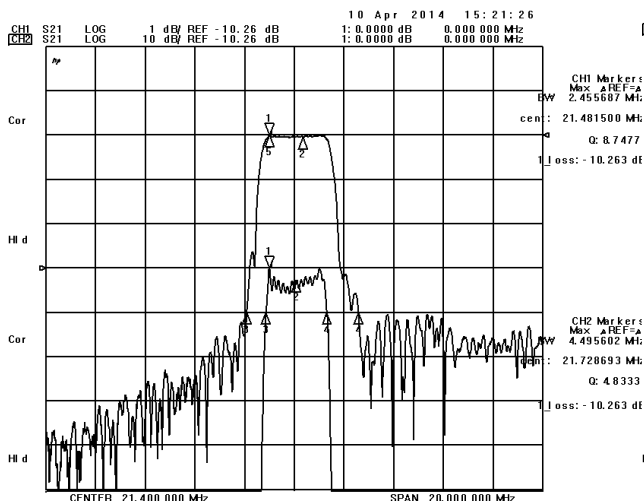


S22 Smith Chart

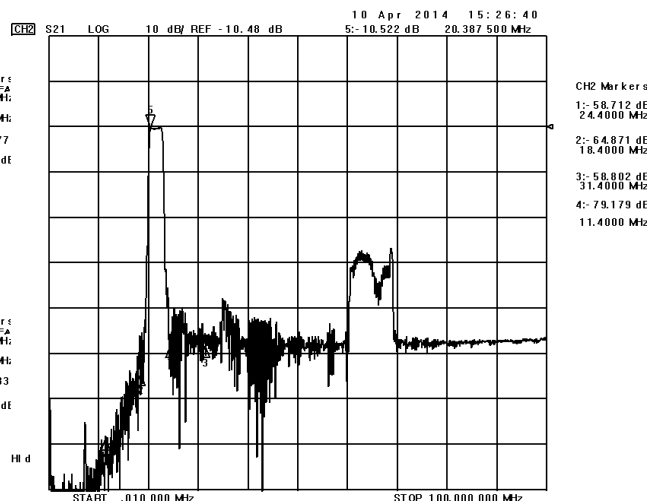


Frequency Characteristics(Case input 6 output 1)

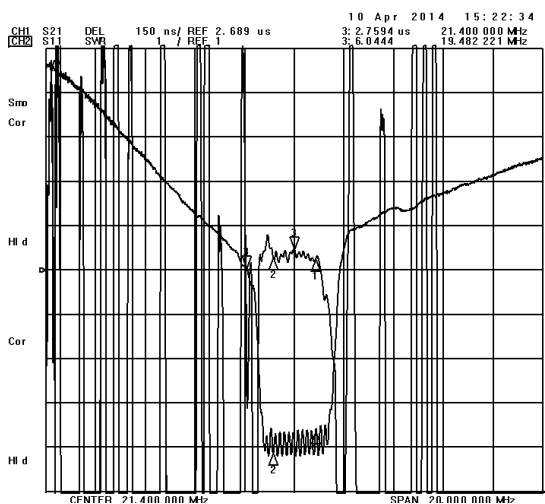
Frequency Response



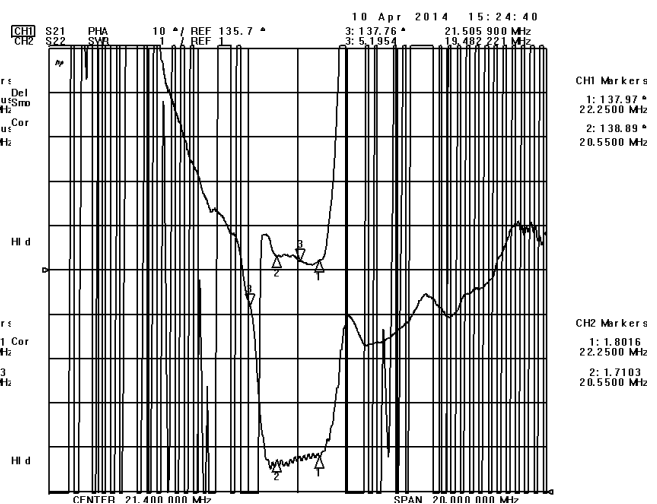
Frequency Response (wideband)



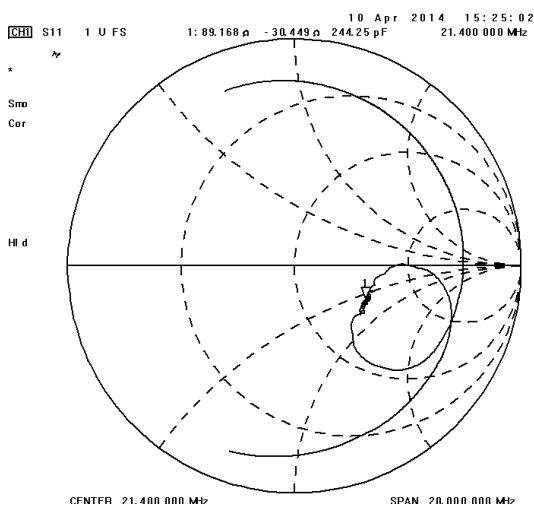
Delay Ripple & S11 VSWR



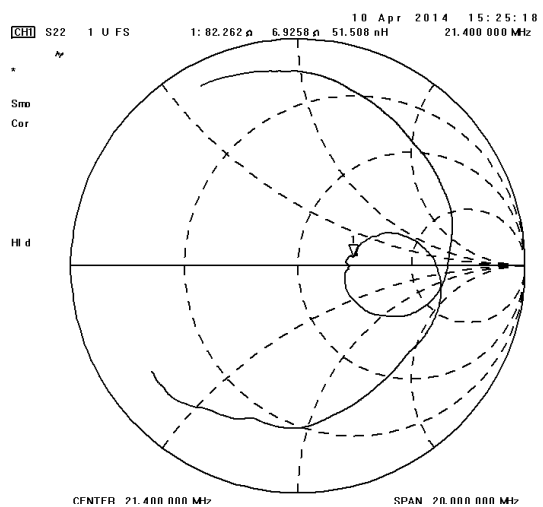
Phase Linearity & S22 VSWR



S11 Smith Chart



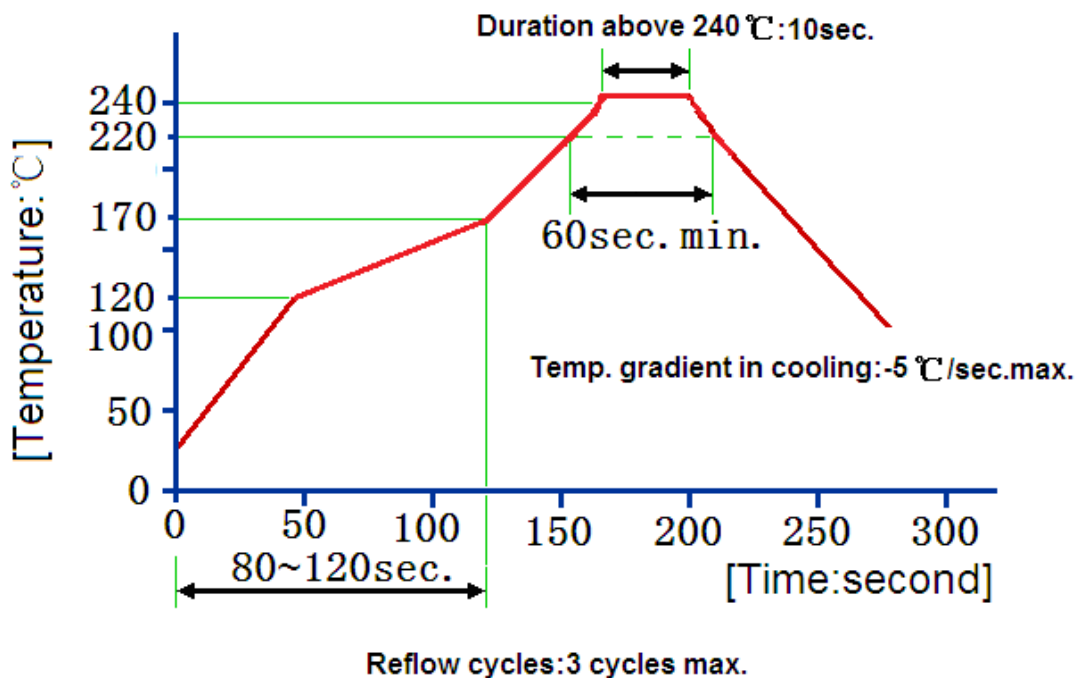
S22 Smith Chart



**Reliability (The SAW components shall remain electrical performance after tests)**

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: 85°C±2°C , Duration: 250h , Recovery time: 2h±0.5h (2) Temperature: -55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h
2	Humidity Test	Conditions: 60°C±2°C , 90~95% RH                          Duration: 250h
3	Thermal Shock	Heat cycle conditions: TA=-55°C±3°C, TB=85°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz                          Amplitude:1.5mm Directions: X,Y and Z    Duration: 2h
5	Drop Test	Cycle time: 10 times    Height: 1.0m
6	Solder Ability Test	Temperature: 245°C±5°C    Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1)Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration: 10±1s (2)Temperature of Soldering Iron: 350°C±10°C , Duration: 3~4s , Recovery time : 2 ± 0.5h

**Recommended Reflow Soldering Diagram**



**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.